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Texas Instruments
LETTER REPORT

SCOPE OF WORKs
Performance evaluation against IPX5 of the “Liquid Tolerant Capacitive Touch Keypad Reference Design with Captivate Technology”

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LETTER REPORT

12/27/2017

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Intertek Project No. G103355606

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Subject: Performance evaluation against IPX5 of the “Liquid Tolerant Capacitive Touch Keypad Reference Design with Captivate Technology”

Dear **Error! Reference source not found.**,

This letter report represents the results of our evaluation of the above referenced product(s) to the requirements contained in the following standards:

Degrees of Protection Provided By Enclosures (IP Code) [IEC 60529:1989 Ed.2+A2; A1; C1; C2; C3; A2; C1; C2]

SECTION 1

SUMMARY

Plano Intertek Testing Services has completed the performance test for the product Liquid Tolerant Capacitive Touch Keypad Reference Design with Captivate Technology.

The test sample was received on 11/17/2017 in good condition. The testing was performed at Intertek in 1809 10th St. Suite 400, Plano, TX 75074 USA, on 11/17/2017 in accordance with the standard “*Degrees of Protection Provided By Enclosures (IP Code) IEC 60529*”.

The objective of test was to demonstrate that the product was able to work properly under IPX5 conditions, the pass criteria consisted of:

- No false triggers during the test or after test
- Accurately detect the button being touched during the test.

The component listed above was found to be in compliance with the performance evaluation.

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LETTER REPORT

SECTION 2

PROJECT STATUS & ACTION

Issuance of this letter report completes the testing portion covered by Intertek Project No. G103355606.

If there are any questions regarding the results contained in this report, or any of the other services offered by Intertek, please do not hesitate to contact your dedicated Intertek Project Engineer.

Completed by:	Felipe Ortiz	Reviewed by:	Bernard Poton
Title:	Compliance engineer	Title:	Engineering Team Leader
Signature:	Felipe Ortiz N	Signature	
Date	12/29/2017	Date:	12/29/2017

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